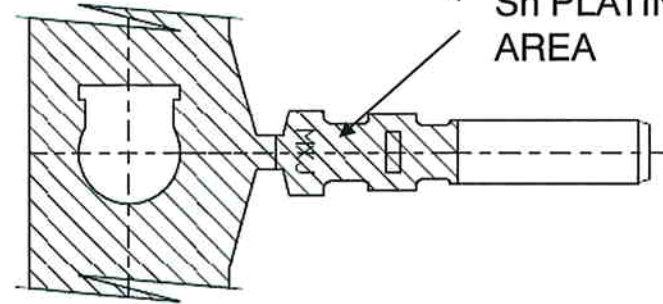
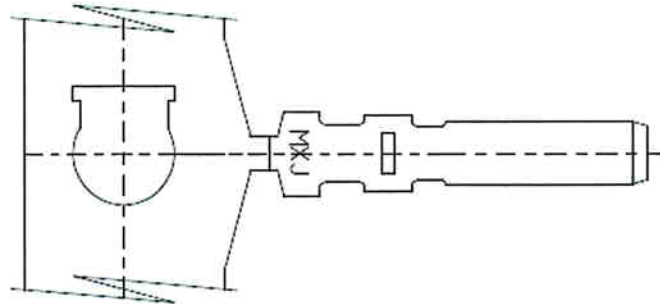
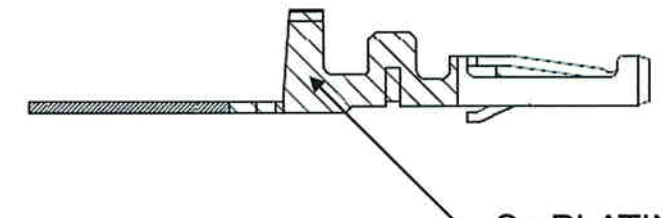
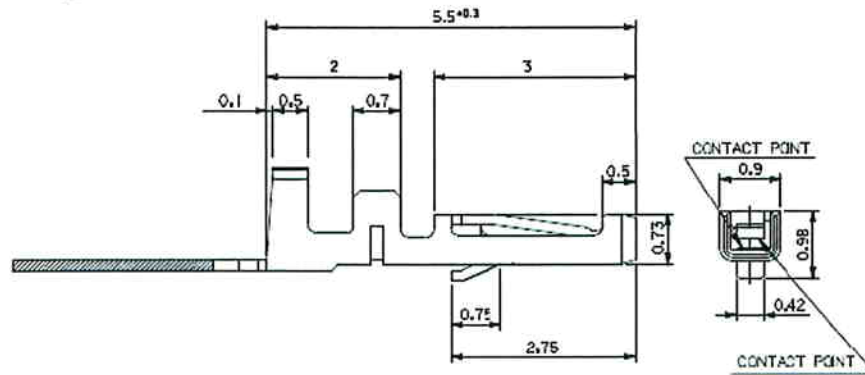
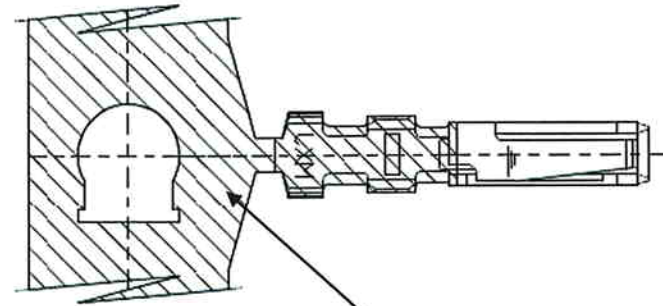
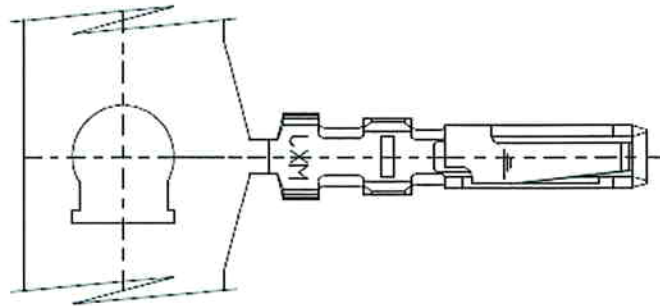


50641-8041 1.25 WB CRIMP REC.
CHANGED PLATING DRAWING

2011/05/10
MOLEX MPD

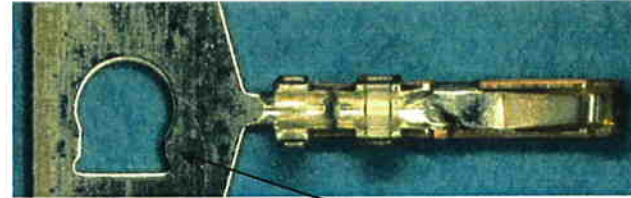


CURRENT PRODUCT
Au:0.2μmMIN.
Ni(UNDER PLATE):1.5μmMIN.

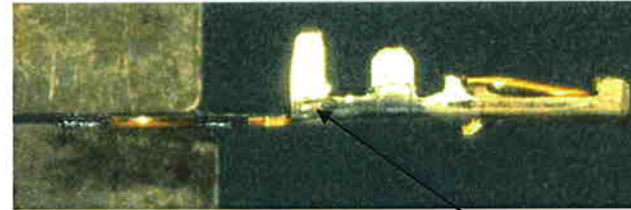


PRE-PLATED PRODUCT
Au(CONTACT AREA):0.2μmMIN.
Sn(HATCHED AREA):0.9μmMIN.
Ni(UNDER PLATE):1.0μmMIN.

50641-8041 1.25 WB CRIMP REC.
CHANGED PLATING PHOTOGRAPH



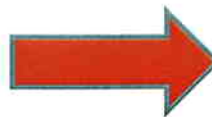
Sn PLATING
AREA



Sn PLATING
AREA



CURRENT PRODUCT
Au:0.2 μ mMIN.
Ni(UNDER PLATE):1.5 μ mMIN.



PRE-PLATED PRODUCT
Au(CONTACT AREA):0.2 μ mMIN.
Sn(HATCHED AREA):0.9 μ mMIN.
Ni(UNDER PLATE):1.0 μ mMIN.